

$V_{RRM} = 2500 \text{ V}$

$I_F = 100 \text{ A}$

Fast-Diode Die

5SLX 12L2510



Die size: 12.4 x 12.4 mm

Doc. No. 5SYA1664-02 Feb. 05

- Fast and soft reverse-recovery
- Low losses
- High SOA
- Passivation: SIPOS Nitride plus Polyimide

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	max	Unit
Repetitive peak reverse voltage	V_{RRM}			2500	V
Continuous forward current	I_F			100	A
Repetitive peak forward current	I_{FRM}	Limited by T_{vjmax}		200	A
Junction temperature	T_{vj}		-40	125	°C

¹⁾ Maximum rated values indicate limits beyond which damage to the device may occur per IEC 60747 - 2

Diode characteristic values ²⁾

Parameter	Symbol	Conditions	min	typ	max	Unit	
Continuous forward voltage	V_F	$I_F = 100 \text{ A}$	$T_{vj} = 25 \text{ °C}$	1.4	1.75	2.0	V
			$T_{vj} = 125 \text{ °C}$		1.8		V
Continuous reverse current	I_R	$V_R = 2500 \text{ V}$	$T_{vj} = 25 \text{ °C}$		1.5		μA
			$T_{vj} = 125 \text{ °C}$		2.5	7	mA
Peak reverse recovery current	I_{rr}	$I_F = 100 \text{ A},$ $V_R = 1250 \text{ V},$ $di/dt = 440 \text{ A}/\mu\text{s},$ $L_\sigma = 1200 \text{ nH},$ Inductive load, Switch: 2x 5SMX12L2510	$T_{vj} = 25 \text{ °C}$		92		A
			$T_{vj} = 125 \text{ °C}$		115		A
Recovered charge	Q_{rr}	$I_F = 100 \text{ A},$ $V_R = 1250 \text{ V},$ $di/dt = 440 \text{ A}/\mu\text{s},$ $L_\sigma = 1200 \text{ nH},$ Inductive load, Switch: 2x 5SMX12L2510	$T_{vj} = 25 \text{ °C}$		57		μC
			$T_{vj} = 125 \text{ °C}$		98		μC
Reverse recovery time	t_{rr}	$I_F = 100 \text{ A},$ $V_R = 1250 \text{ V},$ $di/dt = 440 \text{ A}/\mu\text{s},$ $L_\sigma = 1200 \text{ nH},$ Inductive load, Switch: 2x 5SMX12L2510	$T_{vj} = 25 \text{ °C}$		900		ns
			$T_{vj} = 125 \text{ °C}$		1150		ns
Reverse recovery energy	E_{rec}	$I_F = 100 \text{ A},$ $V_R = 1250 \text{ V},$ $di/dt = 440 \text{ A}/\mu\text{s},$ $L_\sigma = 1200 \text{ nH},$ Inductive load, Switch: 2x 5SMX12L2510	$T_{vj} = 25 \text{ °C}$		54		mJ
			$T_{vj} = 125 \text{ °C}$		92		mJ

²⁾ Characteristic values according to IEC 60747 - 2

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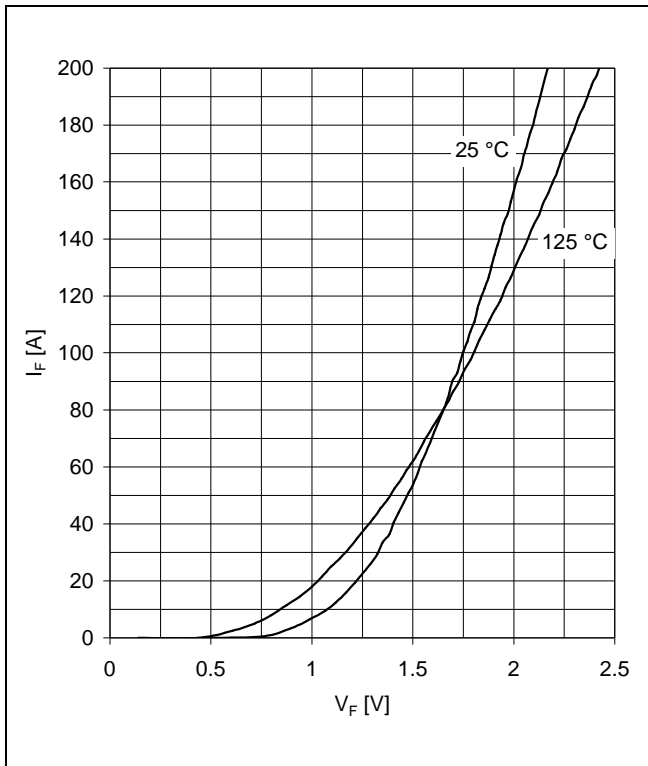


Fig. 1 Typical forward characteristics

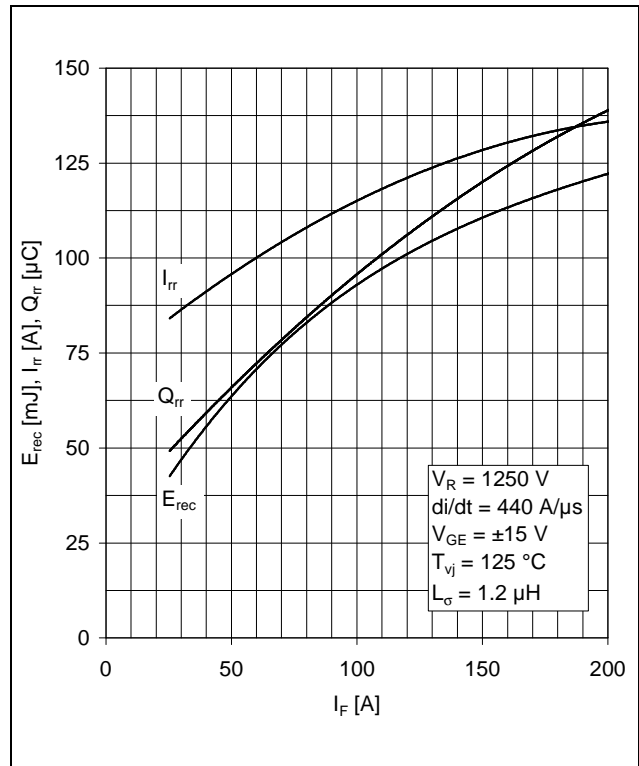


Fig. 2 Typical reverse recovery characteristics vs. forward current

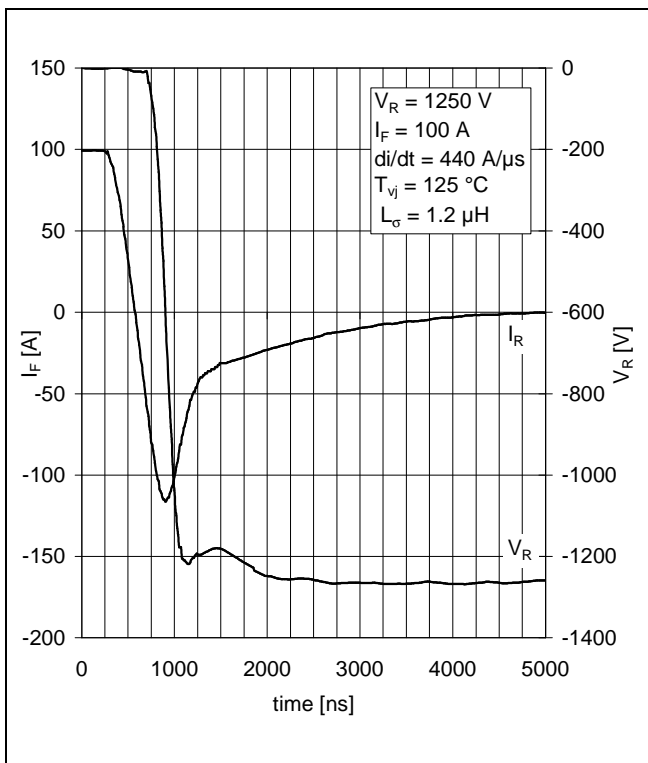


Fig. 3 Typical reverse recovery behaviour

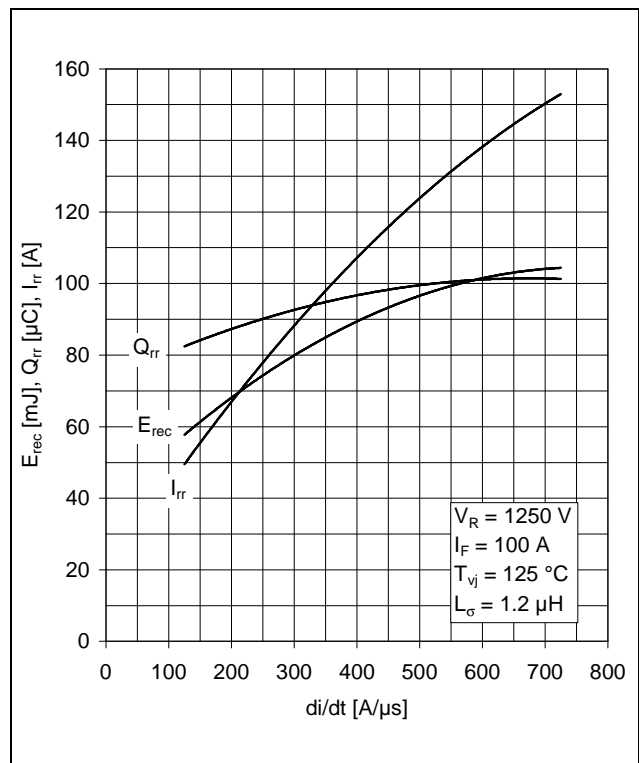


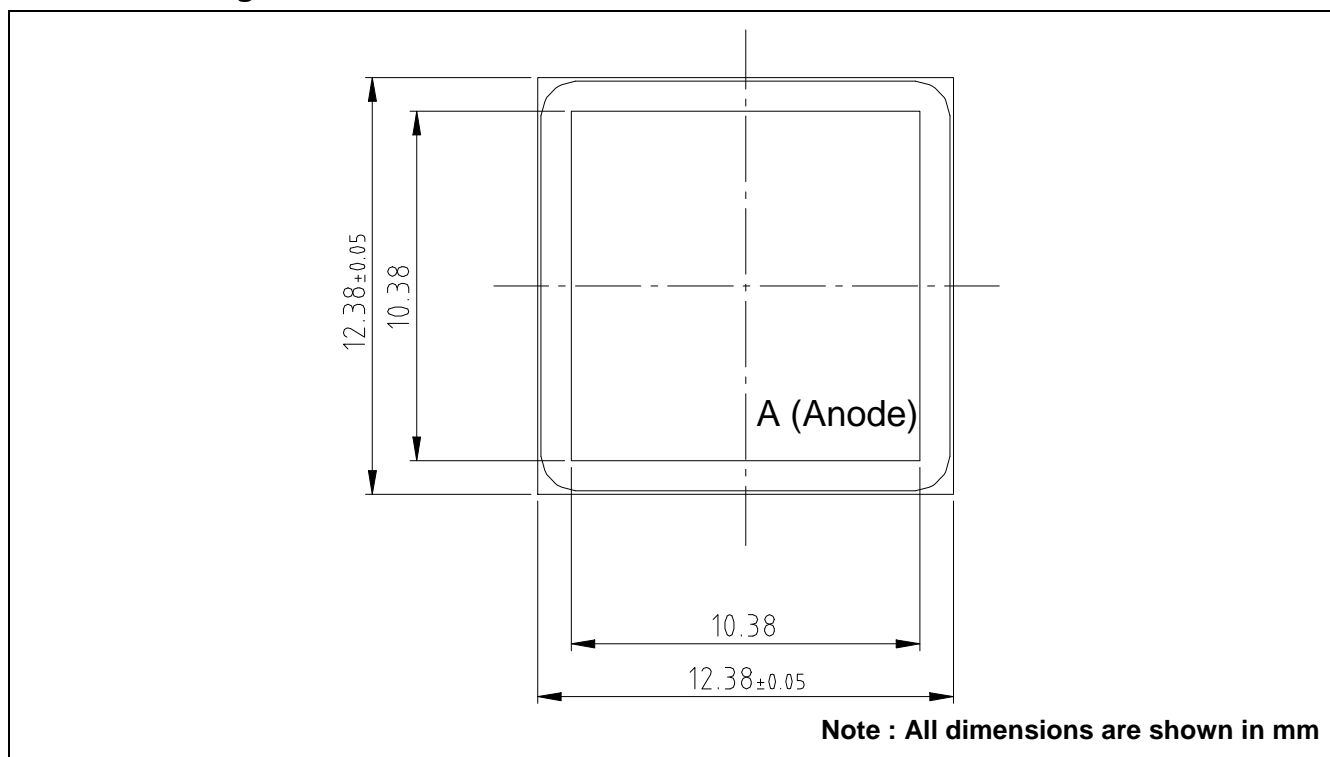
Fig. 4 Typical reverse recovery characteristics vs. di/dt

Mechanical properties

Parameter				Unit
Dimensions	Overall die	L x W	12.4 x 12.4	mm
	exposed front metal	L x W	10.38 x 10.38	mm
	thickness		305 ± 20	µm
Metallization ³⁾	front (A)	AlSi1	4	µm
	back (K)	Al / Ti / Ni / Ag	1.2	µm

³⁾ For assembly instructions refer to: IGBT and Diode chips from ABB Switzerland Ltd, Semiconductors, Doc. No. 5SYA 2033.

Outline Drawing



This product has been designed and qualified for Industrial Level.

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